



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20240402000.1
Qualify HFTF as an additional Assembly site for select devices
Change Notification / Sample Request

Date: April 10, 2024
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within **30 days** of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the Change Management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

Change Management Team
SC Business Services

20240402000.1
Attachment: 1




Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPS54240DGQR	NULL
TPS54260DGQR	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20240402000.1	PCN Date:	April 10, 2024
Title:	Qualify HFTF as an additional Assembly site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	July 09, 2024	Estimated Sample Availability:	May 10, 2024*
*Sample requests received after May 10, 2024 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Material	
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Process	
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Fab Site	
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Material	
<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Process	
PCN Details			
Description of Change:			
Texas Instruments is pleased to announce the qualification of HFTF as an additional Assembly site for the list of devices shown below. Material differences between sites are as follows.			
	UTL2	ASESH	HFTF
Wire type/diam	1.3mil Au, 1.3mil Cu	1.3mil Cu	1.3mil Au
Mount compound	PZ0013	EY1000063	A-24
Mold compound	CZ0094	EN2000515	R-32
Package Outline Differences:			
Existing (UTL2/ASESH)		New (HFTF)	
Reason for Change:			
Continuity of supply.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None.			
Impact on Environmental Ratings			
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.			

RoHS	REACH	Green Status	IEC 62474				
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change				
Changes to product identification resulting from this PCN:							
Assembly Site							
UTL2	Assembly Site Origin (22L)	ASO: NS2					
ASESH	Assembly Site Origin (22L)	ASO: ASH					
HFTF	Assembly Site Origin (22L)	ASO: HFT					
Sample product shipping label (not actual product label)							
   <div style="display: flex; flex-direction: column;"> <div> <p>(1P) SN74LS07NSR</p> <p>(Q) 2000 (D) 0336</p> <p>(31T) LOT: 3959047MLA</p> <p>(4W) TKY (1T) 7523483SI2</p> <p>(P)</p> <p>(2P) REV: (V) 0033317</p> <p>(20L) CSO: SHE (21L) CCO:USA</p> <p>(22L) ASO: MLA (23L) ACO: MYS</p> </div> <div> <p>MADE IN: Malaysia</p> <p>2DC: 20:</p> <table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT:</p> <p>ITEM: 39</p> <p>LBL: 5A (L)T0:1750</p> </div> </div>				MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04
MSL 2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						
Product Affected:							
TPS54240DGQR		TPS54260DGQR					

Qualification Report

Approve Date 25-March-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS54260QDGRQ1	QBS Reference: LM5165XQDGRQ1	QBS Reference: TPS40210QDGRQ1	QBS Reference: SN105070EPNP	QBS Reference: TPS54260QDRCRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0		1/77/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0		-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	3/231/0	-	-		-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	1/45/0	-	-		-
HTSL	A6	High Temperature Storage Life	175C	500 Hours	-	-	-		-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	3/231/0	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	1/15/0	-		-
PD	C4	Physical Dimensions	Cpk>1.67	-	3/30/0	-	-		
ESD	E2	ESD CDM	-	500 Volts	-	-	-		1/3/0
ESD	E2	ESD HBM	-	2000 Volts	-	-	-		1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-		1/3/0
CHAR	E5	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	-	-		3/90/0

QBS: Qual By Similarity
Qual Device TPS54260DGQR is qualified at MSL1 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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